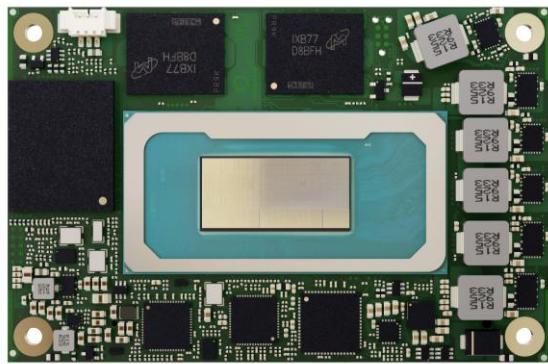


Intel® Core™ Ultra Processors Series 3

conga-MC1000



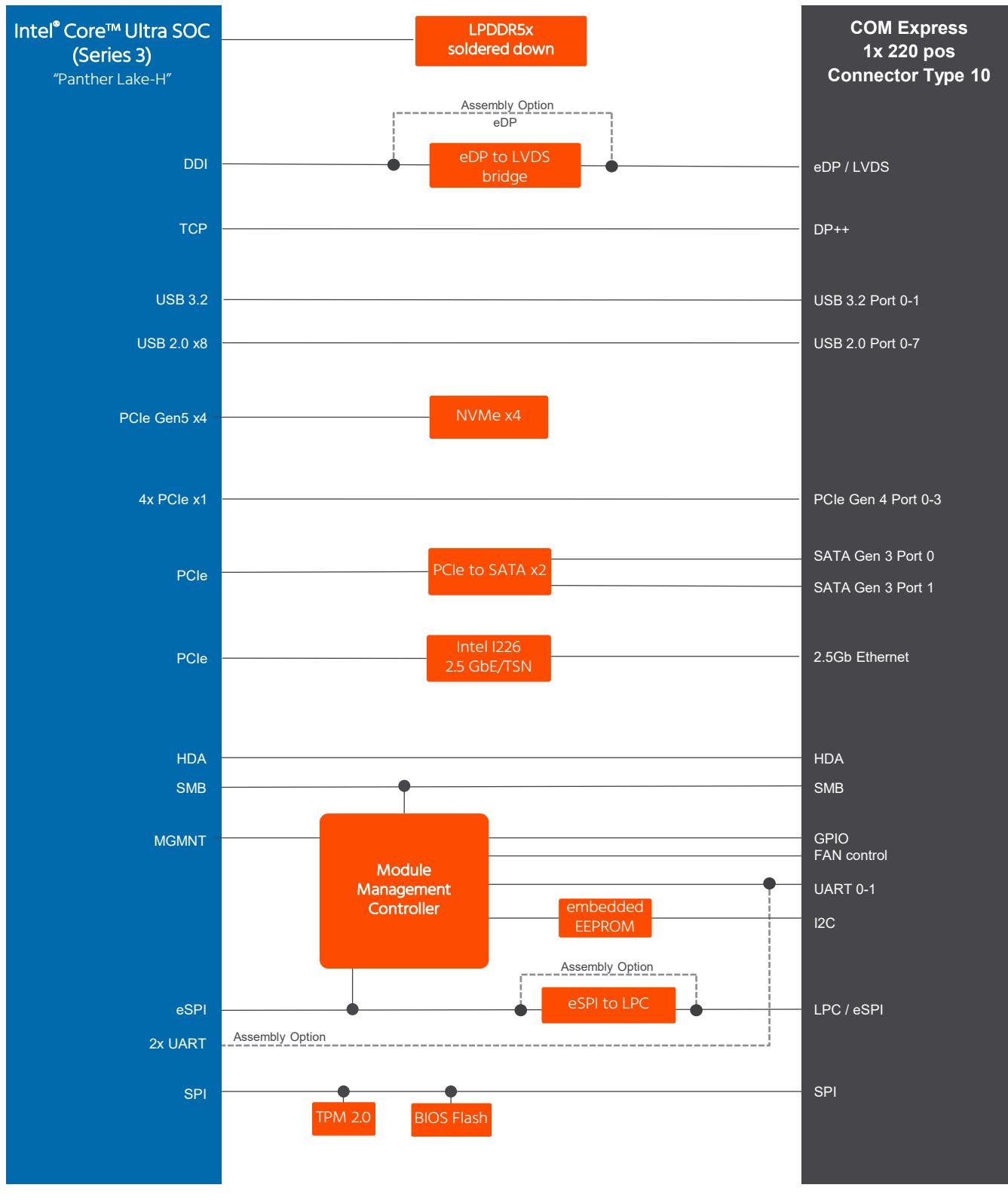
aReady.COM

- Intel® performance hybrid architecture with up to 16 cores
- Intel® Arc™ Graphics with up to 12 X^e cores
- Integrated NPU with up to 50 TOPS and up to 180 TOPS total platform performance
- Up to 32GB LPDDR5x soldered down memory for maximum memory bandwidth

COM  Express[®]

Form factor	COM Express [®] Mini Type 10 connector pinout
CPUs	Intel® Core™ Ultra Processors Series 3 (Panther Lake-H)
DRAM	Up to 32GB LPDDR5x soldered down with up 8533 MT/s In-band ECC (only on selected product variants)
Mass Storage	NVMe up to 1 TB capacity SSD
Graphics	Intel® Arc™ Graphics with up to 12 X ^e cores or Intel Graphics with up to 4 X ^e cores Intel® X ^e Matrix Extensions
AI Acceleration	Integrated NPU accelerator up to 50 TOPS Up to 180 TOPS platform total
Display	DDI for DP++ single-channel LVDS or optional eDP 2x independent displays up to 4k
Ethernet	2.5 GbE via Intel® i226 Ethernet controller series supporting TSN (only on selected product variants)
I/O Interfaces	Up to 4x PCIe Gen4 2x USB 3.2 Gen2 8x USB 2.0 2x SATA 2x UART (RX/TX only) GPIOs GP SPI LPC SM Bus I2C
Audio	High Definition Audio
Module Management Controller	Module Management Controller Multistage Watchdog Board Information Board Statistics I ² C bus (fast mode) Power Loss Control Hardware Health Monitoring POST Code Redirection
Embedded BIOS Feature	AMI Aptio [®] UEFI firmware OEM Logo OEM CMOS default settings LCD Control Display Auto Detection Backlight Control
Security	Trusted Platform Module (TPM 2.0)
Power Management	ACPI 6.0 wide range power supply 8.5V – 20V single supply power
Operating Systems	Microsoft [®] Windows 11 IoT Enterprise Microsoft [®] Windows 11 Linux
Hypervisor	RTS real-time Hypervisor
Temperature	Commercial Temp.: Operating 0°C to 60°C Storage -20°C to 80°C
Humidity	Operating 10% to 85% r. H. non cond. Storage 5% to 85% r. H. non cond.
Size	55 x 84 mm

conga-MC1000 | Block Diagram



Assembly Option

conga-MC1000 | Modules Order Information

Article	PN	Description
conga-MC1000/ultraX9-388H-32G NVMe128	049900	COM Express Mini module based on Intel® Core™ Ultra X9 388H processor with 4 P-cores, 8 E-cores and 4 LPE-cores Integrated NPU 18MB Intel® Smart Cache LLC Intel® Arc™ B390 Graphics with 12X ^e cores LPDDR5x memory module with up to 8533 MT/s and up to 32 GB system memory capacity commercial grade temperature range from 0°C to 60°C.
conga-MC1000/ultra9-386H-32G NVMe128	049901	COM Express Mini module based on Intel® Core™ Ultra 9 386H processor with 4 P-cores, 8 E-cores and 4 LPE-cores Integrated NPU 18MB Intel® Smart Cache LLC Intel Graphics with 4X ^e cores LPDDR5x memory module with up to 8533 MT/s and up to 32 GB system memory capacity commercial grade temperature range from 0°C to 60°C.
conga-MC1000/ultra7-356H-32G NVMe128	049903	COM Express Mini module based on Intel® Core™ Ultra 7 356H processor with 4 P-cores, 8 E-cores and 4 LPE-cores Integrated NPU 18MB Intel® Smart Cache LLC Intel Graphics with 4X ^e cores LPDDR5x memory module with up to 8533 MT/s and up to 32 GB system memory capacity commercial grade temperature range from 0°C to 60°C.
conga-MC1000/ultra5-325-32G NVMe128	049906	COM Express Mini module based on Intel® Core™ Ultra 5 325 processor with 4 P-cores and 4 LPE-cores Integrated NPU 12MB Intel® Smart Cache LLC Intel Graphics with 4X ^e cores LPDDR5x memory module with up to 8533 MT/s and up to 32 GB system memory capacity commercial grade temperature range from 0°C to 60°C.

conga-MC1000 | Accessories Order Information

Article	PN	Description
conga-MC1000/HSP-B	049950	Standard heatspreader for high performance COM Express module conga-MC1000. All standoffs are with 2.7mm bore hole.
conga-MC1000/HSP-T	049951	Standard heatspreader for high performance COM Express module conga-MC1000. All standoffs are M2.5mm threaded.
conga-TEVAL/COMe 3.1	065820	Evaluation carrier board for COM Express Type 6 revision 3.1 modules.